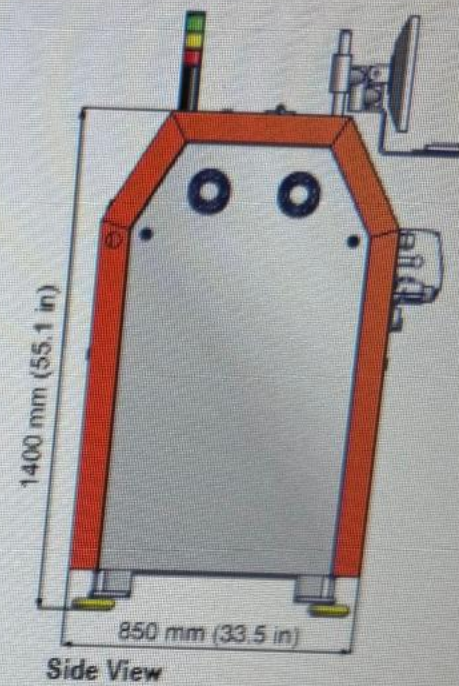
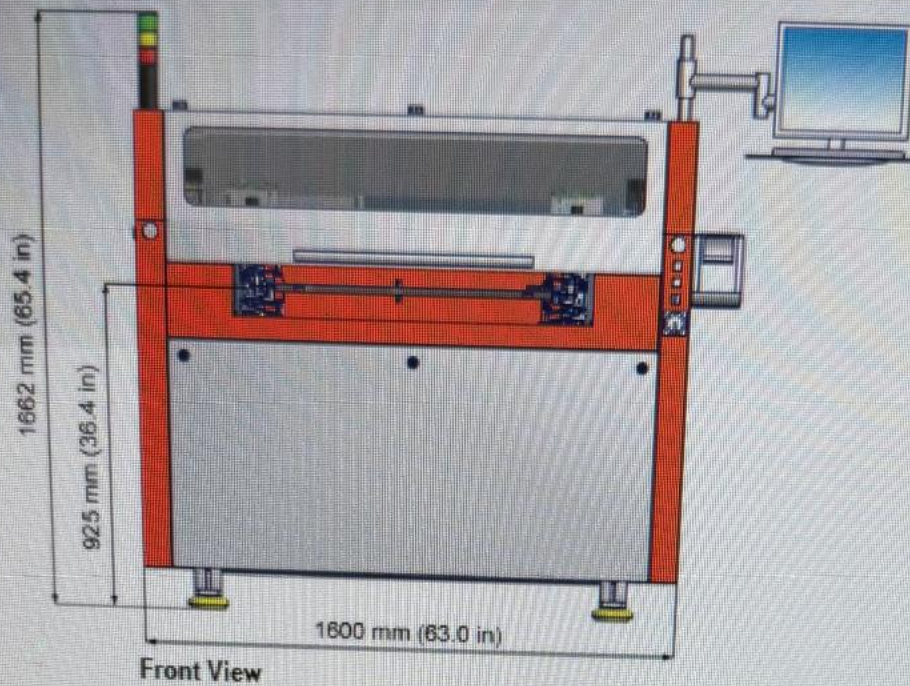




8 Test Heads

Pneumatic Tension Shuttle for Flex and Inner layer handling

Fast 300 mA Kelvin Testing



Mechanics

Basic unit with 8 probes (4 top, 4 bottom)
 Universal shuttle system with clamp and stretch mode for testing flexible and rigid boards. Pneumatic clamping function controlled by foot switch.

Max. board size (X x Y)	640 mm x 495 mm / 25.2" x 19.5"
Min. board size (X x Y)	10 mm x 10 mm / 0.4" x 0.4"
Test area (X x Y)	610 mm x 460 mm / 24.0" x 18.1"
Board thickness	up to 8 mm / 0.32"

Smallest pad	50 μm / 2.0 mil*
Smallest pitch	100 μm / 4.0 mil*
Resolution measurement system	$\pm 0.1 \mu\text{m}$ / ± 0.004 mil
Repeatable accuracy	$\pm 5 \mu\text{m}$ / ± 0.2 mil

*Soft touch probes	5 g to 10 g
or Standard probes	20 g to 100 g

Electronics

Continuity test	1 Ω to 10 k Ω
Isolation test	up to 25 M Ω (FM) up to 100 G Ω (ohmic) MicroShort Detection*
Test voltage	100 mV to 1000 V

Camera System

4 cameras for fast optical scanning of top and bottom side.
 Resolution: 12 megapixel

Options

- 4-wire measurement with max. 300 mA test current

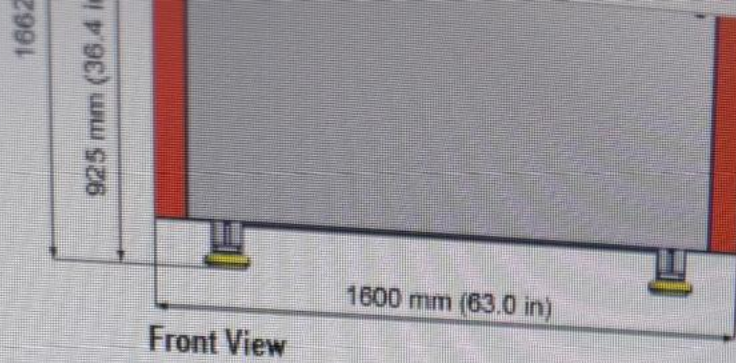
0 Ω to 1 k Ω	± 2 %, min. $\pm 25 \mu\Omega$
with Kelvin probes	0.3 g to 2.5 g
Smallest pad	100 μm / 4.0 mil*
Smallest pitch	150 μm / 6.0 mil*
- Embedded components test

R 0 Ω to 1 M Ω	± 1 %, min. $\pm 0.5 \Omega$
1 M Ω to 200 M Ω	± 3 %
C 0 F to 100 μF	± 2 %, min. ± 30 fF
L 0 H to 10 mH	± 5 %, min. $\pm 0.25 \mu\text{H}$
Diode / Varistor	
U_F , U_R , U_{BR}	0 V to 12.5 V
- LaTest* open detection with LaTest* probes

High current	1 g to 10 g 1.4 A (1 kHz)
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- Retest of fault files from external grid test systems on inquiry
- Repair software with barcode support

Data input format	IPC-D-356A
Network connection	Ethernet, TCP / IP
Power supply	230 V, 50 Hz (115 V, 60 Hz), 900 VA
Compressed air	8 bar / 115 psi, filtered
Temperature	18 $^{\circ}\text{C}$ to 27 $^{\circ}\text{C}$
Relative humidity	40 % to 60 %
Machine weight	700 kg



Mechanics

Basic unit with 8 probes (4 top, 4 bottom)
Universal shuttle system with clamp and stretch mode for testing flexible and rigid boards. Pneumatic clamping function controlled by foot switch.

Max. board size (X x Y)	640 mm x 495 mm / 25.2" x 19.5"
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Board thickness	up to 8 mm / 0.32"
Smallest pad	50 µm / 2.0 mil*
Smallest pitch	100 µm / 4.0 mil*
Resolution measurement system	± 0.1 µm / ± 0.004 mil
Repeatable accuracy	± 5 µm / ± 0.2 mil
*Soft touch probes	5 g to 10 g
or Standard probes	20 g to 100 g

Electronics

Continuity test	1 Ω to 10 kΩ
Isolation test	up to 25 MΩ (FM) up to 100 GΩ (ohmic) MicroShort Detection*
Test voltage	100 mV to 1000 V

Camera System

4 cameras for fast optical scanning of top and bottom side.
Resolution 13 µm/ pixel

Options

- 4-wire measurement with max. 300 mA test current
 - 0 Ω to 1 kΩ ± 2 %, min ± 25 µΩ
 - with Kelvin probes 0.3 g to 2.5 g
 - Smallest pad 100 µm / 4.0 mil*
 - Smallest pitch 150 µm / 6.0 mil*
 - * special setup
- Embedded components test
 - R 0 Ω to 1 MΩ ± 1 %, min. ± 0.5 Ω
 - 1 MΩ to 200 MΩ ± 3 %
 - C 0 F to 100 µF ± 2 %, min. ± 30 fF
 - L 0 H to 10 mH ± 5 %, min. ± 0.25 µH
 - Diode / Varistor
 - U_F, U_R, U_{BR} 0 V to 12.5 V
- LaTest® open detection with LaTest® probes 1 g to 10 g
- High current 1.4 A (1 kHz)

- Retest of fault files from external grid test systems on inquiry
- Repair software with barcode support

Data input format	IPC-D-356A
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All information subject to change without notice!
October 2018